Product Change Notification

107378 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: **107378 - 00**

Change Title: **SR9000MK4U, PCN 107378-00, Product Design, Class 1, Update chipset stepping to Pass3 and CRoHS**

Date of Publication: **March 09, 2007**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	May 08, 2007

Description of Change to the Customer:

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The changes from Pass 2 to Pass 3 chipset stepping include the
following:

a.  PCI-Express bandwidth improvement in a bi-directional (duplex)
environment.
b.  Memory Box (MMR) hot swap for mirrored memory is enabled.
c.  Onboard Video ROM is not used and will be removed.
d.  The SAS controller heat sink will be removed, it is not required
for cooling.
e.  FPGA change to enable future FSB667 support.
f.  MMR part number change and test to enable future FSB667 support.

China RoHS compliance - Adding the EFUP 20 mark to the system safety
label

Part Number Changes:
System:       ES-CF3E-B002 D  to  ES-CF3E-B008 A
Main Board:   ES-CF3E-B032 B  to  ES-CF3E-B036 A
MMR:          ES-CF3E-B100 B  to  ES-CF3E-B106 A
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Customer Impact of Change and Recommended Action:

Customers to place future orders using new order codes, see details in PCN. Customers may also wish to perform re-test, or validation of the product.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change MM#	Post Change TA
SR9000MK4U	885580	D68846-003	890670	D68846-004
A9000MKMEM	886455	D73861-001	890677	D73861-002
F9000MKBRD	886623	D73874-002	890513	D73874-003

Reference Documents / Attachments:

Document:	**Location #:**

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
March 9, 2007	00	Originally Published PCN